LCD / LCM SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司

Winstar Display Co., LTD 華凌光電股份有限公司



WEB: https://www.winstar.com.tw E-mail: sales@winstar.com.tw

SPECIFICATION

CUSTOMER:	
MODULE NO.:	WO256128A-TFH#

APPROVED BY:	AP	PR	OV:	ED	BY:
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(FOR CUSTOMER USE ONLY)

PCB VERSION:

DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED	SUMMAR	RY
		PAGE NO.		
			Modify	the
Н	2024/11/14		recommended	soldering
			temperature	



MODLE NO:

華凌光電股份有限公司

RECORDS OF REVISION

DOC. FIRST ISSUE

VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2015/12/21		First issue
A	2016/01/05		Add External Power
			Supply Circuit.
В	2016/01/27		Modify Precautions in use
			of LCD Modules
			& Static electricity test
С	2016/11/21	χ^{C}	Add FPC bending rule
D	2019/08/27		Modify Material List of
			Components for RoHs
Е	2019/12/17		Modify Precautions in use
			of LCD Modules
F	2020/08/28		Add Interface
	MY		Modify Contour drawing
G	2022/12/21		Modify B/L information
H	2024/11/14		Modify the recommended
			soldering temperature

Contents

- 1.Module Classification Information
- 2.Precautions in use of LCD Modules
- 3.General Specification
- 4. Absolute Maximum Ratings
- 5. Electrical Characteristics
- 6. Optical Characteristics
- 7.Interface Pin Function
- 8. Contour Drawing & Block Diagram
- 9.Reliability
- 10.Backlight Information
- 11.Inspection specification
- 12. Material List of Components for RoHs
- 13.Recommendable Storage
- 14.Other

WO256128A-TFH#

1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type, X→TAB Type, O→COG Type

③ Display Font: 256 * 128 dot

Model serials no.

 $B\rightarrow EL$, Blue green $A\rightarrow LED$, Amber $J\rightarrow DIP$ LED, Blue $D\rightarrow EL$, Green $R\rightarrow LED$, Red $K\rightarrow DIP$ LED, White

W→EL, White O→LED, Orange E→DIP LED, Yellow Green

 $M\rightarrow$ EL, Yellow Green $G\rightarrow$ LED, Green $H\rightarrow$ DIP LED, Amber $F\rightarrow$ CCFL, White $P\rightarrow$ LED, Blue $I\rightarrow$ DIP LED, Red

 $Y \rightarrow LED$, Yellow Green $X \rightarrow LED$, Dual color $G \rightarrow LED$, Green $C \rightarrow LED$, Full color

© LCD Mode : B→TN Positive, Gray V→FSTN Negative, Blue

N→TN Negative, T→FSTN Negative, Black

L→VA Negative D→FSTN Negative (Double film)

 $H \rightarrow HTN$ Positive, Gray $F \rightarrow FSTN$ Positive $I \rightarrow HTN$ Negative, Black $K \rightarrow FSC$ Negative $U \rightarrow HTN$ Negative, Blue $S \rightarrow FSC$ Positive

M→STN Negative, Blue E→ISTN Negative, Black
G→STN Positive, Gray C→CSTN Negative, Black
Y→STN Positive, Yellow Green A→ASTN Negative, Black

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

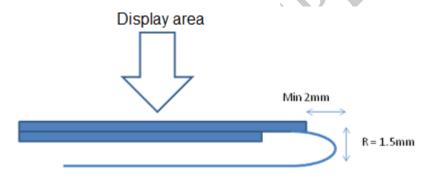
Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00 range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00 direction J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00 E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code #:Fit in with the ROHS Directions and regulations

2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11) The limitation of FPC bending



(12)Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

3.General Specification

Item	Dimension	Unit
Number of dots	256 x 128	_
Module dimension	80.0 x 54.0 x 9.5	mm
View area	70.7 x 38.8	mm
Active area	66.54 x 33.26	mm
Dot size	0.24 x0.24	mm
Dot pitch	0.26 x 0.26	mm
LCD type	FSTN Positive Transflective (In LCD production, It will occur slightly color can only guarantee the same color in the same be	
Drive Method	1/128 DUTY,1/12 BIAS	
View direction	6 o'clock	
Backlight Type	LED, White	
IC	ST75256i	. /
Interface	4-Line SPI/IIC/8-bit 6800/8-bit 8080	

4.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T_{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}$
MPU Interface Input Voltage	Vin	-0.3	_	V _{DD} +0.3	V
Digital Power Supply Voltage	V _{DD} -Vss	-0.3	_	4.0	V
LCD Power supply voltage	V0- XV0	-0.3	_	19.0	V

5.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$ m V_{DD} ext{-}V_{SS}$	_	3.0	3.3	3.6	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCM	$ m V_{OP}$	Ta=25°C	14.2	14.5	14.8	V
		Ta=70°C	_	_	\	v
Input High Volt.	$ m V_{IH}$	_	$0.7~\mathrm{V_{DD}}$	_	V_{DD}	V
Input Low Volt.	V_{IL}	_	V_{SS}	7	0.3 V _{DD}	V
Output High Volt.	V_{OH}	_	$0.8~\mathrm{V_{DD}}$		$V_{ m DD}$	V
Output Low Volt.	V_{OL}	- 1	V _{SS}	_	$0.2~\mathrm{V_{DD}}$	V
Supply Current	I_{DD}	V _{DD} =3.3V		1.5	_	mA

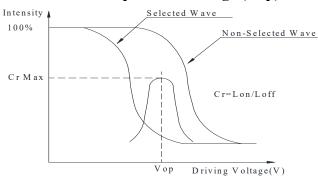
Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.



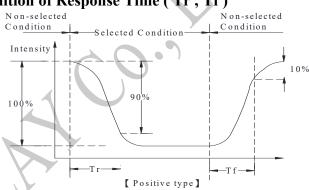
6.Optical Characteristics

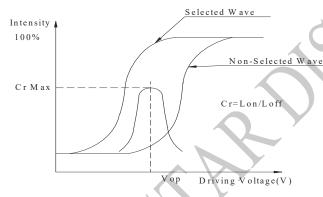
Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	30	$\phi = 180^{\circ}$
View Angle	θ	CR≧2	0	_	60	$\phi = 0^{\circ}$
	θ	CR≧2	0	_	45	$\phi = 90^{\circ}$
	θ	CR≧2	0	_	45	$\phi = 270^{\circ}$
Contrast Ratio	CR	_	_	5	_	_
D T'	T rise	_	_	200	300	ms
Response Time	T fall	_	_	250	350	ms

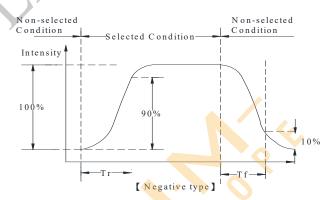
Definition of Operation Voltage (Vop)



Definition of Response Time (Tr, Tf)







Conditions:

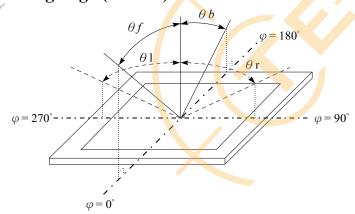
Operating Voltage: Vop

Viewing Angle(θ , φ): 0° , 0°

Frame Frequency: 64 HZ

Driving Waveform: 1/N duty, 1/a bias

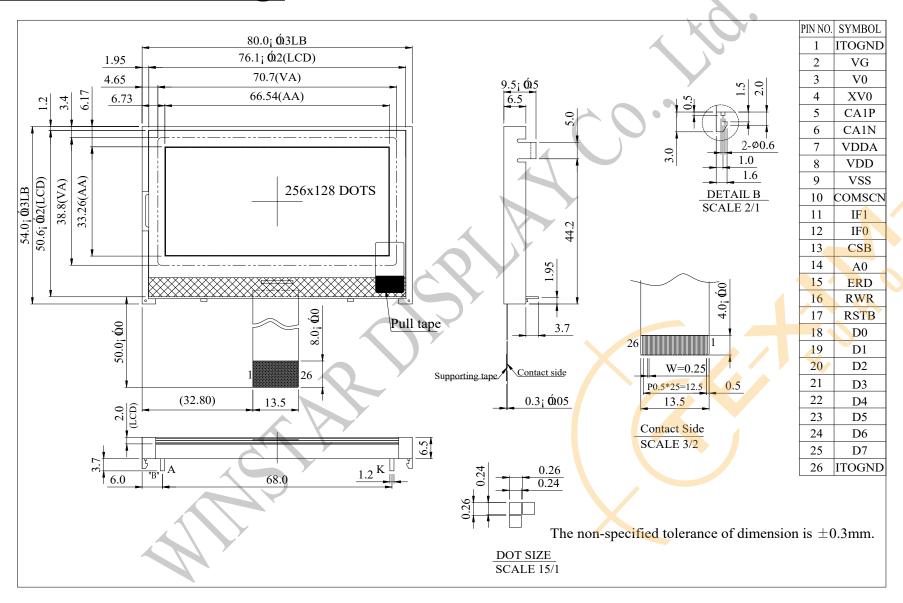
Definition of viewing angle ($CR \ge 2$)



7.Interface Pin Function

Pin No.	Symbol			Description		
1	ITOGND	ESD PIN	1			
2	VG	Power of	f SEG-d	rivers		
3	V0	Positive	operatin	g voltage of COM-drivers		
4	XV0	Negative	e operati	ng voltage of COM-drivers		
5	CA1P	DC/DC	Voltage	converte pin		
6	CA1N	DC/DC	Voltage	converte pin		
7	VDDA	+3.3V		△ O •)		
8	VDD	+3.3V		4		
9	VSS	ground				
10	COMSCN	Set scan	directin	g of COM		
11	IF1	These pi	ns select	interface operation mode.		
		IF1	IF0	MPU interface type		
		L	L	4-line serial interface		
12	IF0	L	Н	IIC serial interface		
12	110	H	L	8-bit 6800 parallel interface		
		H	H	8-bit 8080 parallel interface		
		Note: Ref	er to "Par	allel / Serial Interface'' for detailed information.		
13	CSB	Chip sel	ect input	t pin		
14	A0	Whether	the acce	ess is related to data or command		
15	ERD	Read or	write en	able terminal		
16	RWR	Read/Write execution control pin				
17	RSTB	Reset input pin				
18~25	D0~D7	Data bus	line			
26	ITOGND	ESD PIN	1			

8.Contour Drawing



9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test								
Test Item	Content of Test	Test Condition	Not e					
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs ▲	2					
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2					
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	_					
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1					
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2					
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation $-20^{\circ}\text{C} \qquad 25^{\circ}\text{C} \qquad 70^{\circ}\text{C}$ 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles						
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3					
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times						

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

10.Backlight Information

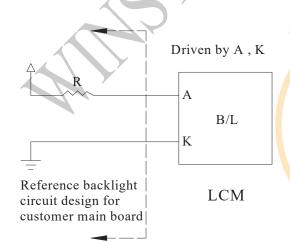
Specification

Parameter	Symbol	Min	Тур	Max	Unit	Test Condition
Supply Current	ILED	_	96	120	mA	V=3.5V
Supply Voltage	V	3.3	3.5	3.7	V	- 3
Reverse Voltage	VR	_	_	5	V	- 1
	X	0.24	0.27	0.30		V. 25V
Colour coordinate	Y	0.24	0.27	0.30		V=3.5V
Luminance (Without LCD)	IV	840	1050	-	cd/m²	ILED=96mA
LED Life Time (For Reference only)	_	-	50K		Hr.	ILED=96mA 25°C,50-60%RH, (Note 1)
Color	White				•	

Note: A backlight driven by voltage will keep the drive current under the safe area (current between minimum and maximum).

If the B/L LED is driven by current only, the drive voltage cannot be considered as a reference value.

Note 1:50K hours is only an estimate for reference.



11.Inspection specification

No	Item	Criterion					
		Missing vertical, horizontal segment, segment contrast defect.					
		Missing character, dot or icon.					
		Display malfunction.					
01	Electrical	No function or no display.					
01	Testing	Current consump	tion exce	eds product specific	ations.	0.65	
		LCD viewing angle defect.					
		Mixed product types.					
		Contrast defect.					
	Black or white	2.1 White and bla	ack spots	on display ≤ 0.25 m	m, no more than		
02	spots on LCD	three white or bla	ack spots	present.		2.5	
	(display only)	2.2 Densely spac	ed: No m	ore than two spots o	or lines within 3mm		
		3.1 Round type:	As follow	ving drawing			
		$\Phi = (x + y) / 2$					
		X		Size	Acceptable QTY		
		3	44	Φ≦0.10	Accept no dense	2.5	
		7	F Y	$0.10 < \Phi \le 0.20$	2		
	LCD black spots,			$0.20 < \Phi \leq 0.25$	1		
02	white spots,			0.25 < Ф	0		
03	contamination	3.2 Line type : (As following drawing)					
	(non-display)				Acceptable Q	4	
		v¥ w	Length	Width	TY	Q	
				W≦0.02	Accept no dense	2.5	
	3	L	L≦3.0	$0.02 < W \le 0.03$	1 1 0		
			L≦2.5	$0.03 < W \le 0.05$	2		
		•		0.05 < W	As round type		
,4							
		If bubbles are vis	sible,	Size Φ	Acceptable Q TY		
		judge using black	spot	$\Phi \leq 0.20$	Accept no dense		
04	Polarizer bubbles	specifications, no	ot easy	$0.20 < \Phi \leq 0.50$	3	2.5	
		to find, must che	ck in	$0.50 < \Phi \le 1.00$	2		
		specify direction.		1.00<Φ	0		
				Total Q TY	3		

No	Item	Criterion				
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination				
			Glass thickness a: LC	p thickness D side length		
		6.1 General glass chip: 6.1.1 Chip on panel sur	face and crack between	panels:		
		z: Chip thickness	y: Chip width	x: Chip length		
	Chipped	Z≦1/2t	Not over viewing area	x≤1/8a		
06	glass	$1/2t < z \leq 2t$	Not exceed 1/3k	x≤1/8a	2.5	
		⊙ If there are 2 or more 6.1.2 Corner crack:	chips, x is total length o		2	
	19	z: Chip thickness	y: Chip width	x: Chip length		
		Z≦1/2t	Not over viewing area	x≤1/8a		
	,	$1/2t < z \le 2t$	Not exceed 1/3k	x≤1/8a		
		⊙ If there are 2 or more chips, x is the total length of each chip.				

Item	Criterion	AQL				
	Symbols:					
	x: Chip length y: Chip width z: Chip thickness					
	k: Seal width t: Glass thickness a: LCD side length					
	L: Electrode pad length					
	6.2 Protrusion over terminal:					
	6.2.1 Chip on electrode pad:					
Class	$\begin{array}{ c c c c c }\hline y : Chip \ width & x : Chip \ length & z : Chip \ thickness \\\hline y \le 0.5 mm & x \le 1/8a & 0 < z \le t \\\hline 6.2.2 \ Non-conductive portion: \\ \\ L \\ \\ \\ L \\$					
Glass crack	y $\uparrow z$ y $\downarrow x$ $\uparrow z$	2.5				
	y: Chip width x: Chip length z: Chip thickness					
	$y \le L \qquad \qquad x \le 1/8a \qquad \qquad 0 < z \le t$					
	OIf the chipped area touches the ITO terminal, over 2/3 of the ITO must					
		K				
	6.2.3 Substrate protuberance and internal crack.					
~	v: width x: length					
	y X X					
	Glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:				

No	Item	Criterion	AQL		
07	Cracked glass	The LCD with extensive crack is not acceptable.			
		8.1 Illumination source flickers when lit.	0.65		
0.0	Backlight	8.2 Spots or scratched that appear when lit must be judged. Using	2.5		
08	elements	LCD spot, lines and contamination standards.			
		8.3 Backlight doesn't light or color wrong.	0.65		
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5		
09	Bezel	stains or other contamination.			
		9.2 Bezel must comply with job specifications.	0.65		
		10.1 COB seal may not have pinholes larger than 0.2mm or	2.5		
		contamination.			
		10.2 COB seal surface may not have pinholes through to the IC.	2.5		
		10.3 The height of the COB should not exceed the height	0.65		
		indicated in the assembly diagram.			
		10.4 There may not be more than 2mm of sealant outside the seal	2.5		
		area on the PCB. And there should be no more than three places.			
		10.5 No oxidation or contamination PCB terminals.			
		10.6 Parts on PCB must be the same as on the production	2.5		
10	PCB · COB	characteristic chart. There should be no wrong parts, missing	0.65		
		parts or excess parts.			
		10.7 The jumper on the PCB should conform to the product			
		characteristic chart.	0.65		
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or			
		screw hold pad, make sure it is smoothed down.	2.5		
		10.9 The Scraping testing standard for Copper Coating of PCB	25		
		X	2.5		
	46	$X * Y \le 2mm^2$			
		11.1 No un-melted solder paste may be present on the PCB.	2.5		
	1	11.2 No cold solder joints, missing solder connections, oxidation	2.5		
11	Soldering	or icicle.			
	1/4	11.3 No residue or solder balls on PCB.	2.5		
		11.4 No short circuits in components on PCB.	0.65		

NO	Item	Criterion	
NO	Item	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 	0.65 2.5 2.5 2.5
12	General appearance	12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet.	2.5 2.5 2.5 0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65

12.Material List of Components for

RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited	100	1000	1000	1000	1000	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm
Above limited value is set up according to RoHS.										

- 2. For RoHS compliance, the recommended soldering temperatures for different components are as follows:
- (1) FPC: 300°C, 1-3 seconds
- (2) Backlight AK and metal pin glass: 330°C, 1-5 seconds

Note: Customers should adjust the temperature and duration based on the actual materials used in their soldering process, including the soldering iron, solder paste, and any other components involved.

13.Recommendable Storage

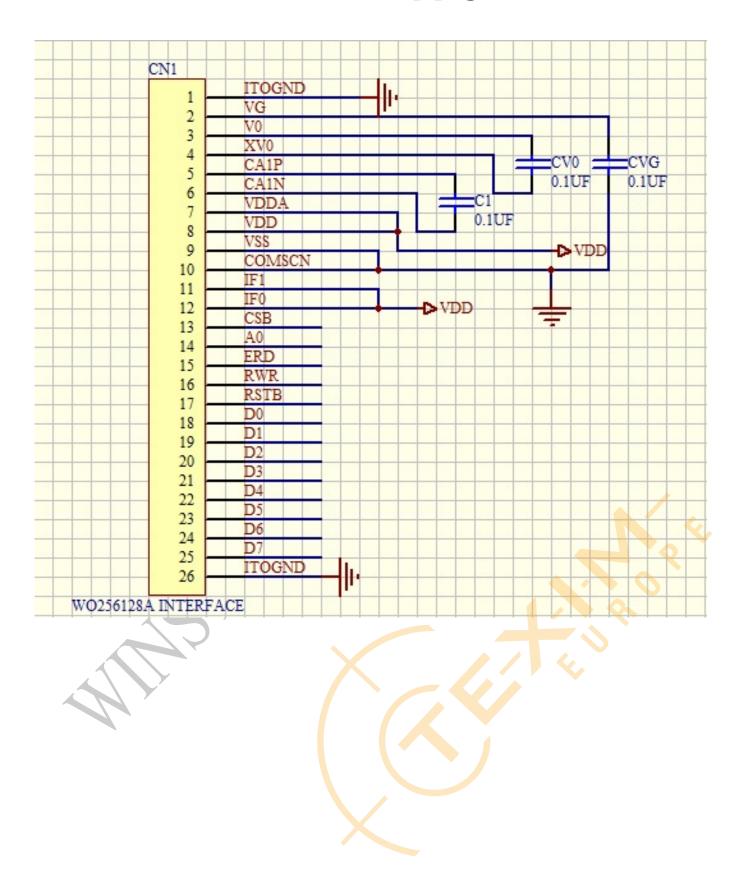
- 1. Place the panel or module in the temperature 25°C \pm 5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



winstar <u>LCM Samp</u> Ioaule Number:	ole Estimate	Feedback Sheet Page: 1
1 · Panel Specification :	_	G
1. Panel Type:	☐ Pass	□ NG ,
2. View Direction:	Pass	□ NG ,
3. Numbers of Dots:	Pass	□ NG ,
4. View Area:	Pass	□ NG ,
5. Active Area:	Pass	□ NG ,
6. Operating Temperature:	Pass	□ NG ,
7. Storage Temperature:	Pass	□ NG ,
8. Others:		
2 · Mechanical Specification:		
1. PCB Size:	☐ Pass	□ NG ,
2. Frame Size:	☐ Pass	□ NG ,
3. Materal of Frame:	Pass	□ NG,
4. Connector Position:	Pass	□ NG ,
5. Fix Hole Position:	Pass	□ NG ,
6. Backlight Position:	☐ Pass	□ NG ,
7. Thickness of PCB:	☐ Pass	□ NG ,
8. Height of Frame to PCB:	☐ Pass	□ NG ,
9. Height of Module:	☐ Pass	□ NG ,
10. Others:	☐ Pass	□ NG ,
3 · Relative Hole Size :		
1. Pitch of Connector:	☐ Pass	□ NG ,
2. Hole size of Connector:	Pass	□ NG ,
3. Mounting Hole size:	Pass	□ NG,
4. Mounting Hole Type:	☐ Pass	□ NG,
5. Others:	☐ Pass	□ NG ,
4 · Backlight Specification :		
1. B/L Type:	Pass P	□ NG ,
2. B/L Color:	Pass	□ NG,
3. B/L Driving Voltage (Refer	ence fo <mark>r</mark> LED	Type): Pass NG,
4. B/L Driving Current:	☐ Pass	□ NG ,
5. Brightness of B/L:	☐ Pass	□ NG ,
6. B/L Solder Method:	☐ Pass	□ NG ,
7. Others:	Pass	□ NG ,
	>> Go to	page 2 <<

odule Number :		Page: 2		
5 · Electronic Characteristics of	f Module:			
1. Input Voltage:	Pass	□ NG ,		
2. Supply Current:	Pass	□ NG ,		
3. Driving Voltage for LCD:	Pass	□ NG ,		
4. Contrast for LCD:	☐ Pass	□ NG ,		
5. B/L Driving Method:	Pass	□ NG ,		
6. Negative Voltage Output:	Pass	□ NG,		
7. Interface Function:	Pass	□ NG ,		
8. LCD Uniformity:	Pass	□ NG ,		
9. ESD test:	Pass	□ NG,		
10. Others:	☐ Pass	□ NG ,		
5 · <u>Summary</u> :				
(6)				
Sales signature:				
Customer Signature:		Date : / /		

14.External Power Supply Circuit



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Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time.

All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts.

Please contact us if you have any questions about the contents of the datasheet.

This may not be the latest version of the datasheet. Please check with us if a later version is available.



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